PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7227122

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YI FANG LEE	08/06/2021
JAYDIP GUHA	07/20/2020
LARS P. HEINECK	06/22/2020
KAMAL M. KARDA	03/15/2022
SI-WOO LEE	06/18/2020
TERRENCE B. MCDANIEL	06/18/2020
SCOTT E. SILLS	08/24/2021
KEVIN J. TOREK	06/18/2020
SHENG-WEI YANG	07/06/2020

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY, MS 1- 525
City:	BOISE
State/Country:	IDAHO
Postal Code:	83716

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16934607

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ATTORNEY DOCKET NUMBER:	MI22-7294
NAME OF SUBMITTER:	BRIDGET WISEMAN

SIGNATURE:	/Bridget Wiseman/
DATE SIGNED:	03/16/2022

Total Attachments: 12
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ASSIGNMENT

PARTIES TO THE ASSIGNMENT:

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ASSIGNEE:

Micron Technology, Inc.
MS 1-525
8000 South Federal Way
Boise, ID 83716
United States

BACKGROUND OF THIS ASSIGNMENT:

Inventors have conceived certain new and useful inventions disclosed in a United States patent application titled "Array Of Vertical Transistors And Method Used In Forming An Array Of Vertical Transistors".

Micron Technology, Inc. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent(s) that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of good and valuable consideration, the receipt, sufficiency and adequacy of which is hereby acknowledged, INVENTORS have sold, assigned and transferred, and by these present do hereby sell, assign and transfer to ASSIGNEE the entire right, title and interest in the above-identified inventions and patent application(s) and to any reissues, renewals, divisions or continuations of the application(s) thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such

Letters Patent(s) to ASSIGNEE for the sole use of ASSIGNEE, its successors or assigns.

INVENTORS further agree to execute, at the request and expense of ASSIGNEE, such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any patent application papers (foreign or domestic) required for the filing of any divisional, continuation, renewal or reissue of the patent application(s) or resulting Letters Patent(s); and will generally do everything necessary or desirable to obtain and enforce proper protection for the inventions assigned hereby.

INVENTORS further assign to ASSIGNEE the whole right, title and interest in the inventions disclosed in the application(s) throughout all countries foreign to the United States. ASSIGNEE is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTORS agree to execute application(s) relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent(s) to ASSIGNEE as well as all other necessary papers in relation to such applications and Letters Patent(s). INVENTORS hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country as proof of the right of ASSIGNEE to apply for patent and other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Dated: 08/06/2021 Signature: Yi Fang Lee.
Yi Fang Lee

Dated: 7/20/2020

Signature: Jaydip Guha

Jaydip Guha

Dated: June 22, 2020 Signature:

Lars P. Heineck

Dated: 03/15/22 Signature:

Kamal M. Karda

Dated: 8/18/20 Signature:
Si-Woo Lee

Dated: 8/18/2020

Signature: Terrence B. McDaniel

Dated: 08/24/2021 Signature: ________________
Scott E. Sills

Dated: 6/10/20 Signature:
Kevin J. Zorek

Dated: 7/11/2020 Signature: Shengwei Yang
Sheng-Wei Yang